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## United States Patent [19]

## Milina

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[54]	EDGE BEAD REMOVAL GAP GAUGE		
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[56]	References Cited		
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## [57] ABSTRACT

An apparatus and method for determining the distance of a semiconductor wafer from a nozzle of an edge bead removal system. A rotationally adjustable gap gauge is placed over a vacuum chuck of an edge bead removal system. The gap gauge has a ramped surface which is located proximate to the nozzle when the gap gauge is placed over the vacuum chuck. By rotating the gap gauge on the vacuum chuck, the ramped surface is brought closer to the nozzle. When the nozzle contacts the ramped surface, the position of the gap gauge, as shown by calibration marks on the gap gauge, are recorded. The calibration marks on the gap gauge indicate the corresponding distance that will exist between the nozzle and the backside of a semiconductor wafer when the gap gauge is removed and a semiconductor wafer is placed onto the vacuum chuck. The edge bead removal system is then adjusted such that a desired distance will exist between the nozzle and a semiconductor wafer when a semiconductor wafer is placed onto the vacuum chuck. In so doing, the present claimed invention provides for uniform quantitative measurement of the gap distance between a nozzle and the backside of a semiconductor wafer in an edge bead removal system.

6 Claims, 3 Drawing Sheets

